







LE FONDS EUROPÉEN DE DÉVELOPPEMENT RÉGIONAL ET LA WALLONIE INVESTISSENT DANS VOTRE AVENIR



# Why do we need life cycle thinking in the context of the Internet-of-Things (IoT) ?

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### **UCLouvain** ICT helpful for many uses...





cteam

### **UCLouvain** But, at the same time ...

#### Global total net CO<sub>2</sub> emissions

Billion tonnes of CO<sub>2</sub>/yr







Source : IPBES 2019



A1 Nature is essential for human existence and good quality of life. Most of nature's contributions to people are not fully replaceable, and some are irreplaceable. Nature plays a critical role in providing food

A4 Nature across most of the globe has now been significantly altered by multiple human drivers, with the great majority of indicators of ecosystems and biodiversity showing rapid decline. Seventy-five per

**A8** Human-induced changes are creating conditions for fast biological evolution – so rapid that its effects can be seen in only a few years or even more quickly. The consequences can be positive or negative for biodiversity and ecosystems, but can create uncertainty about the sustainability of species, ecosystem functions and the delivery of nature's contributions to people.

Huge challenge : very few trials to get it right + short period

of time (30 years) -> today's actions are critical



Lunden, MDPI Sustainability, 2018



However, this DOES NOT include the carbon footprint of IoT !



What are the environmental impacts of a massive deployment of IoT devices ?



## UCLouvain Life Cycle Thinking



□ Life Cycle Thinking aims at considering the (environmental) impacts of a device or service over its whole life cycle.

□ Life Cycle Assessment (LCA) is a wellknown methodology (ISO14040-4) supporting this goal in practice.



# Why do we need life cycle thinking in the context Of IoT ?



Outline



□ Introduction & context

### □ Modeling the environmental impacts of IoT devices

- The carbon footprint of IoT production [JCP-2021]
- A multi-indicators cradle-to-grave LCA of wireless power transfer (WPT) [In writing]

Conclusions and perspectives

□ Open discussions, Q&A

LCA of IoT

### Carbon footprint of IoT edge devices



## Carbon footprint of IoT edge devices



**OUR CONTRIBUTION** 

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### Carbon footprint of IoT edge devices https://doi.org/10.1016/j.jclepro.2021.128966

### Main question :

How to model the embodied carbon footprint for a wide range of IoT edge devices while preserving precision?

### **Our contribution :**

- **Framework (quantitative)** to streamline the carbon footprint of IoT edge devices production
- Addresses directly the **heterogeneity** of the IoT and the lack of work in this field
- **Transparency** to foster the use of the framework
- Benchmarked with existing results (sparse)
- Applied on 4 use-cases



### Carbon footprint of IoT edge devices

### **IoT hardware profiles :**

- High level of details for each hardware specification level.
- Based on data sheets, review of literature and reports, teardowns and expertise.
- Not exhaustive but covers already a wide range of IoT hardware.
- Main gaps: sensing and actuation could be improved, energy harvesting was not considered

#### Table 1

Detailed life-cycle inventory (LCI) for IoT hardware profiles. For each hardware specification level, lower/typical/upper parameters considered are given. If not mentioned explicitly, all data is taken from GaBi professional and GaBi Extension XI (Electronics) databases. All the modeling is carried out in the GaBi LCA software. Additional details are provided in the supplementary material.

Punctional block	Definition	Pefnition Hardware specification level (HSL)					
		HSL-0	HSL-1		HSL-2	HSL-3	
Actuators	Components that physically act on the environment	No actuator	ctuator Vibration m		Relay (SSR) 1/2/4	DC motor (50g) 1/4/6 Motor driver <sup>b</sup> 1/2/5 mm <sup>2</sup> Motor driver transistor 1/4/6	
Casing	Structural components of the IoT edge device whose primary function is to protect the electronic components	No casing	ABS pla Aluminu Steel 1/	stic granulate 10/50/100 g m 1/10/30 g 10/30 g	ABS plastic granulate 200/400/500 g Aluminum 20/80/150 g Steel 20/80/150 g	ABS plastic granulate 700/80 Steel 70/160/300 g	0,900 g
Connectivity	Components which are involved in data transmission	Embedded in Processing (share of the die area) Printed antenaa (embedded in PCB)	Connectivity IC <sup>e</sup> 5/10/20 mm <sup>2</sup> Printed antenna (embedded in PCB)		Connectivity IC <sup>d</sup> 20/30/45 mm <sup>2</sup> External whip-like antenna 10/15/30 g	Connectivity 1C <sup>d</sup> 45/50/60 mm <sup>2</sup> External whip-like antenna 10/15/30 g	
Memory	Components involved in the data storage on the IoT edge device	Embedded in Processing, Flash + RAM (= kB)	DRAM <sup>8</sup> (32/128/512 MB) 2/7.9/31.5 mm <sup>2</sup> Flash <sup>f</sup> (32/128/512 MB) 0.2/0.8/3.2 mm <sup>2</sup>		DRAM <sup>8</sup> (0.5/1/2 GB) 31.5/61.5/123.1 mm <sup>2</sup> Flach <sup>f</sup> (1/4/8 GB) 6.3/25/50 mm <sup>2</sup>	$ \begin{array}{l} \text{DRAM}^{6} \ (0.5/1/2 \ \text{GB}) \ 31.5/61.5/123.1 \ \text{mm}^2 \\ \text{Flash}^{f} \ (8/16/32 \ \text{GB}) \ 50/100/200 \ \text{mm}^2 \end{array} $	
Others	The rest of the components which do not fit another functional block	Capacitors and resistson 5/10/15 Diodes 2/2/2, transitions 1/2/3 Tantahan capacitors 0/0/2, crystals 0/1/1	Capacitors and resistors 15/20/25 Diodes 2/4/6, transitors 2/4/6 Tatabam capacitos 0.0/3 Crystals 11/2 Steel meal shield 0.5/1/2 g Cables 1/2/5 cm		Capacitors and resistors 40/50/60 Diodes 2/4/6, transistors 4/7/9 Tambiam capacitors 0,0/4 Crystais 1/2/4 Steel metai absidi 0.5/1/2 g Cables 1/2/5 cm	Capacitors and resistors 75/85/100 Diodes 2/6/10, transistors 7/10/15 Tantitium capacitors 0/2/4 Crystals 1/2/4 Steel metal shield 0.5/1/2 g Cables 1/2/5 em	
POB	Components responsible for the electro-mechanical support and electrical connections between electronic components of the IoT edge device.	FR4 (4 layers) 8/10/15 cm <sup>2</sup> Solder Paste (SAC305) 4/8/13 mg	FR4 (4 Solder I	layers) 15/35/50 cm <sup>2</sup> aate (SAC305) 28/53/98 mg	n) 15/25/50 cm <sup>2</sup> PM (9 Jappe) 80/20/ m (8AC305) 28/53/98 mg Solder Pare (8AC305) 99/155/249 mg Solder Pare (8AC305) 5		m <sup>2</sup> 65/454 mg
Power supply	Composent involved in the energy source and energy management of the 10T edge device, which could be battery-powered or main-powered	Mains powered Power Stanistics 2/3/4 Diodes power 0/1/2 Radial capacitor 2/3/4 Ministure on 0/2/3/4 Ring core onl 0/1/1.5 m C282 //4 Khuko plag 0/1/1	1 Coin alkaline	eell 1476/2 AAA aikailae/2 A	Li don bartey <sup>2</sup> 10,50,700 g Power transitor 0/1/2 Diddes power 0/1/2 Radial capaciter 0/1/2 Miniature coil 0/1/2	LAon barry <sup>1</sup> 10,50/100 g Powe transitor 0/1/2 Diode power 0/1/2 Radia dyactor 0/1/2 Miniature 0/8 0/1/2 External 107 0/15/25 mm <sup>2</sup>	
Processing	Components involved in the data processing and control tasks on the IoT edge device	MCU <sup>c</sup> 5/10/17 mm <sup>2</sup>	App licat Auxi liar	ion processor <sup>12</sup> 20/30/45 mm <sup>2</sup> y MCU <sup>c</sup> //10/17 mm <sup>2</sup>	Application processor <sup>6</sup> $50/60/75 \text{ mm}^2$ Auxiliary MCU <sup>6</sup> $5/10/17 \text{ mm}^2$	Application processor <sup>e</sup> 75/10 Auxiliary MCU <sup>c</sup> 5/10(17 mm	0/125 mm <sup>2</sup> 2
Security	Components related to cryptography and protection of sensitive data	Embedded in Processing or non-existent	External	K <sup>h</sup> 1/2/3 mm <sup>2</sup>	N/A	N/A	
Sensing Transport	Components involved in measuring physical quantifies of the environment Related to the shipping of the assembled IoT edge device from the factory to the consumer	No seasor No transport	Electre Transp Track ( Plane d Total y	Capacitors and resistors 40/50/60 Diodes 2/4/6, transistors 4/7/9			mm <sup>2</sup> 3") 8/30/58 mm <sup>2</sup> t am 0 km 8
User interface	Components allowing interactions between external users and the IoT edge device	No user interface	Switch- LED 1,	Tantalum capacitors 0/0/4			
<sup>8</sup> OMOS 0.25 µm; <sup>b</sup> CMOS 0.13 µm; <sup>6</sup> CMOS 90 nm; <sup>6</sup> CMOS 22 nm; <sup>6</sup> CMOS 14 nm; <sup>f</sup> Flash 45 nm; <sup>8</sup> DRAM 57 nm; <sup>b</sup> Dzza from AUO (3)				Crystals 1/2/4			
				Steel metal shield 0.5/1/2 g			
				Cables 1/2/	/5 cm		1
							-

### Carbon footprint of IoT edge devices



### Carbon footprint of IoT edge devices https://doi.org/10.1016/j.jclepro.2021.128966

### **Results :**

- Values are given for each hardware specification level.
- The framework can be easily used to streamline the carbon footprint of other IoT edge devices thanks to the hardware profiles.
- The carbon footprint of simple and complex devices can vary by a factor more than 150× according to our framework





used

### Carbon footprint of IoT edge devices https://doi.org/10.1016/j.jclepro.2021.128966

#### Applying the framework on 4 use-cases :

- (1) an occupancy sensor; (2) a smart watch; (3) a home-connected assistant (Google Home MINI); and (4) a drone (Mavick MINI)
- Less specific than a dedicated LCA but already provides a detailed modeling
- Different hot-spots depending on the hardware profile : all IoT devices are not equal !



### Carbon footprint of IoT edge devices https://doi.org/10.1016/j.jclepro.2021.128966

#### Limitations

- Truncation error due to the bottom-up approach (well-known issue)
- Strong lack of details in other studies to enable a fair and detailed comparison
- Focuses only on the production + a single indicator (GWP)  $\rightarrow$  **not sufficient**
- GaBi (Sphera) databases are not open source



## Carbon footprint of IoT edge devices

### Second question :

How coherent is the massive deployment of devices with the Paris Agreement (PA) objectives ?



### Carbon footprint of IoT edge devices https://doi.org/10.1016/j.jclepro.2021.128966

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### **Results**:

**Conflicting paths** with PA (scenarios)  $\rightarrow$  critical need to integrate LCA for IoT: trade-off between the type of profile and the number of devices



## Carbon footprint of IoT edge devices

### Second question :

How coherent is the massive deployment of devices with the Paris Agreement (PA) objectives ?

### **Results**:

**Conflicting paths** with PA (scenarios)  $\rightarrow$  critical need to integrate LCA for IoT: trade-off between the type of profile and the number of devices



## LCA of WPT (wireless power transfer)



#### **OUR CONTRIBUTION**

#### Main question :

How does a state-of-the-art WPT system compare to a battery-powered system in terms of environmental impacts ?

### **Our contribution :**

- Comparative LCA (cradle-to-grave). Specific modeling of the two setups.
- LCA needed for 4 indicators : PED, GWP, EcoTox, Water.

[core of the paper: Marco Gonzalez et al.]

- PIR sensor for room occupancy monitoring consuming 4 μW
- Sensor supplied with 2.45-GHz WPT at 3.5m from the RPH (cold-start)







**Smart** 

sensor

### **Results :**

- Environmental impacts of WPT are significantly higher compared to the equivalent setup using a battery (coin cell). Lifetime is assumed to be 10 years.
- WPT system yields higher absolute impacts, i.e. from 5.6× to 6.7×.

User

interface

Bluetooth

receiver

Information gateway

**1**x



### **Results**:

- Environmental impacts of WPT are significantly higher compared to the equivalent setup using a battery (coin cell). Lifetime is assumed to be 10 years.
- WPT system yields higher absolute impacts, i.e. from  $5.6 \times$  to  $6.7 \times$ .
- Increasing the number of smart sensors (up to 8) generally strengthen the previous conclusions, with impacts up to **10.9**× higher.





Conclusions

### **Conclusions**

### Why do we need **life cycle thinking** in the context of **IoT** ?

- □ IoT is a **fast growing** subpart of ICT and implies a massive deployment of electronics: the environmental impacts generated **must be better understood**.
- □ There is a high degree of heterogeneity in IoT devices: **all IoT devices are not equal**.
- LCA for electronics also embeds limitations and blind spots: current modeling only provides a downgraded picture of the reality. More expertise and research is needed in this field. Carbon footprint is only one (dark) side of environmental impacts (e.g. the total amount of WEEE keeps increasing every year (>10 Mt in 2019 for IT [GEM, 2020])
- □ **Take home message for IoT designers:** include environmental considerations during the development of your technical solution and investigate further than the use phase.

### **Conclusions**

### What LCA also looks like in practice:

- **Teardowns** (including IC desoldering)
- In-house die inspection (destructive + microscopes) for very specific LCA (while low latency/cost)
- **PCB** design on EAGLE
- Power measurements in WELCOME (AC and DC)



### Perspectives: one step at a time ...



#### Last step (TO DO)



#### **TO BE INCLUDED**

This talk



- How to integrate LCA during the design of IoT systems ? What about eco-design ? Could we imagine the IoT to be fully designed-for-reuse or designed-for-X ?
- □ What about the end-of-life of IoT devices ? What will be the impact on WEEE management ?
- There is a trend towards edge-computing: what will be the impacts from a life cycle thinking analysis ?
- □ Technology development and rebound effects : how do they interact ?

□ ...

# Thank you

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# Open discussion & feedbacks